

SMP75

Trisil™ for telecom equipment protection

Features

- bidirectional crowbar protection
- voltage: 8 V
- low leakage current: I_R = 2 µA max
- holding current: I_H = 150 mA min
- repetitive peak pulse current: I_{PP} = 75 A (10/1000 µs)

Benefits

- Trisils are not subject to ageing and provide a fail safe mode in short circuit for a better protection.
- This device can be used to help equipment to meet main standards such as UL1950, IEC 950 / CSA C22.2 and UL1459.
- Trisils have UL94 V0 approved resin.
- SMB package is JEDEC registered (DO-214AA).
- Trisils comply with the following standards:
 - GR-1089 Core
 - ITU-T-K20/K21
 - VDE0433
 - VDE0878
 - IEC 61000-4-5
 - FCC part 68

Applications

Any sensitive equipment requiring protection against lightning strikes and power crossing:

- Ethernet,
- T1/E1

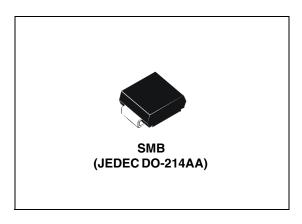
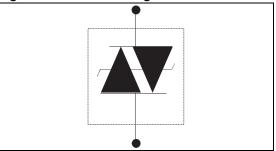


Figure 1. Device configuration



Description

The SMP75 is a very low voltage transient surge arrestor especially designed to protect sensitive telecommunication equipment against lightning strikes and other transients. Its low voltage makes it suitable to protect low voltage transformer in T1/E1 and Ethernet links without saturation of the transformer.

TM: Trisil is a trademark of STMicroelectronics.

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Characteristics SMP75

1 Characteristics

Table 1. In compliance with the following standards

Standard	Peak surge voltage (V)	Waveform voltage	Required peak current (A)	Current waveform	Minimum serial resistor to meet standard (Ω)
GR-1089 Core	2500	2/10 μs	500	2/10 μs	5
First level	1000	10/1000 µs	100	10/1000 µs	3.3
GR-1089 Core Second level	5000	2/10 µs	500	2/10 µs	10
GR-1089 Core Intra-building	1500	2/10 µs	100	2/10 µs	0
ITU-T-K20/K21	ITILT K20/K21 6000		150 10/700 µs	5/310 µs	10
TTO TILEOTIET	1500	10/700 μο	37.5	0/010 μο	0
ITU-T-K20	8000	1/60 ns	ESD contact discharge		0
(IEC61000-4-2)	15000	1/00 113	ESD air o	0	
VDE0433	4000	10/700 µs	100	5/310 µs	0
VDE0433	2000	10/700 μs	50	5/310 μs	0
VDE0878	4000	1.2/50 µs	100	1/20 µs	0
VDE0676	2000	1.2/50 μS	50	1/20 μs	0
IEC61000-4-5	4000	10/700 μs	100	5/310 µs	0
IEC61000-4-5	4000	1.2/50 µs	100	8/20 μs	0
FCC Part 68, lightning	1500	10/160 μs	200	10/160 μs	2.5
surge type A	800	10/560 μs	100	10/560 μs	0
FCC Part 68, lightning surge type B	1000	9/720 µs	25	5/320 µs	0

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Table 2. Absolute ratings ($T_{amb} = 25 \text{ °C}$)

Symbol	Parameter	Value	Unit	
I _{PP}	Repetitive peak pulse current	10/1000 µs 8/20 µs 10/560 µs 5/310 µs 10/160 µs 1/20 µs 2/10 µs	75 250 100 120 150 250	A
I _{FS}	Fail-safe mode : maximum current (1)	8/20 μs	5	kA
I _{TSM}	Non repetitive surge peak on-state current (sinusoidal)	t = 0.2 s t = 1 s t = 2 s t = 15 mn	14 8 6.5 2	А
I ² t	I2t value for using	t = 16.6 ms t = 20 ms	12 12.2	A²s
T _{stg}	Storage temperature range	-55 to + 150	°C	
Tj	Maximum junction temperature	150	°C	
T_L	Maximum lead temperature for soldering during 10 s.		260	°C

^{1.} In fail safe mode, the device acts as a short circuit.

Table 3. Thermal resistances

Symbol	Parameter	Value	Unit
R _{th(j-a)}	Junction to ambient (with recommended footprint)	100	°C/W
R _{th(j-l)}	Junction to leads	20	°C/W

Table 4. Electrical characteristics - definitions ($T_{amb} = 25$ °C)

Symbol	Parameter	
V_{RM}	Stand-off voltage	1.
V_{BR}	Breakdown voltage	
V_{BO}	Breakover voltage	
I _{RM}	Leakage current	I 80
I _{PP}	Peak pulse current	I _{RM}
I _{BO}	Breakover current	V_{RM} V_{BR} V_{BO}
I _H	Holding current	/
V _R	Continuous reverse voltage	
I _R	Leakage current at V _R	\mathcal{L}
С	Capacitance	

Characteristics SMP75

Table 5.	Electrical	characteristics -	values	$(T_{amb} = 25 ^{\circ}C)$
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	I _{RM} @	V _{RM}	I _R ⁽¹⁾ @ V _R		Dynamic Static VBO VBO BO			l _H	C ⁽²⁾
Order code	max.		max.		max.	max.	max.	typ.	max.
	μΑ	V	μΑ	V	V	V	mA	mA	pF
SMP75-8	2	6	5	8	20	15	800	50	60

- 1. I_R measured at V_R guaranteed V_{BR} min $\geq V_R$
- 2. $V_R = 2 V \text{ bias}, V_{RMS} = 1 V, F = 1 MHz$

Figure 2. Pulse waveform

Repetitive peak pulse current $t_r = \text{rise time } (\mu s)$ $t_p = \text{pulse duration time } (\mu s)$ $t_r = \text{pulse duration time } (\mu s)$

Figure 3. Non repetitive surge peak on-state current versus overload duration

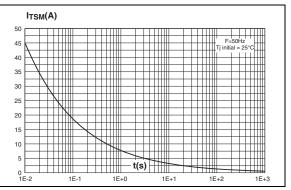
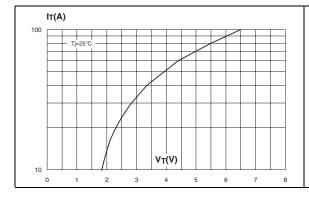
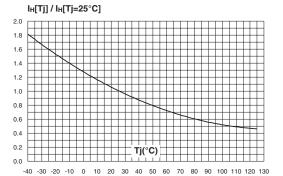


Figure 4. On-state voltage versus on-state current (typical values)

Figure 5. Relative variation of holding current versus junction temperature



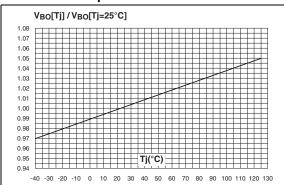


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Figure 6. Relative variation of breakover voltage versus junction temperature

Figure 7. Relative variation of leakage current versus reverse voltage applied (typical values)



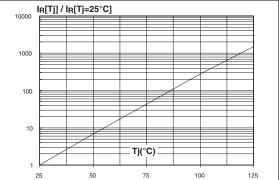
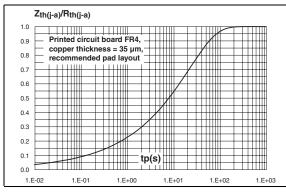
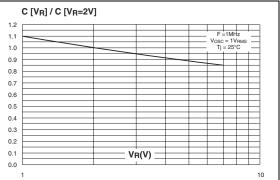


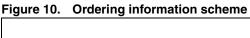
Figure 8. Variation of thermal impedance junction to ambient versus pulse duration

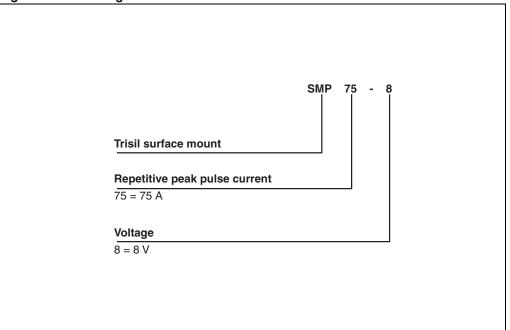
Figure 9. Relative variation of junction capacitance versus reverse voltage applied (typical values)





Ordering information scheme 2





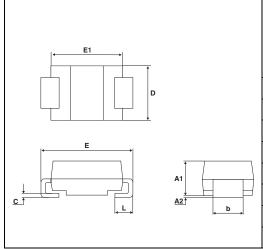
SMP75 Package information

3 Package information

- Epoxy meets UL94, V0
- Lead-free package

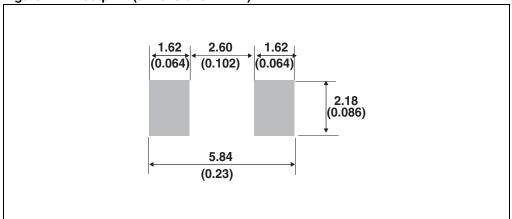
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 6. SMB Dimensions



		Dimensions				
Ref.	Millim	Millimeters		hes		
	Min.	Max.	Min.	Max.		
A1	1.90	2.45	0.075	0.096		
A2	0.05	0.20	0.002	0.008		
b	1.95	2.20	0.077	0.087		
С	0.15	0.40	0.006	0.016		
D	3.30	3.95	0.130	0.156		
Е	5.10	5.60	0.201	0.220		
E1	4.05	4.60	0.159	0.181		
L	0.75	1.50	0.030	0.059		

Figure 11. Footprint (dimensions in mm)



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4 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
SMP75-8	L08	SMB	0.11 g	2500	Tape and reel

5 Revision history

Table 8. Document revision history

Date	Revision	Changes
19-July-2005	3	Previous issue
02-Jan-2006	4	Added ECOPACK statement and changed page layout. Minor updates to technical values in Tables 1, 2, and 4.
19-Oct-2010	5	Updated ECOPACK statement. Updated trademark statement. Updated <i>Figure 11</i> . Removed Section 2 Test circuits.

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